

WHAT IS CLAIMED IS:

1. A method of manufacturing tape circuit boards, said method comprising:
 - (a) providing an insulating base film having first and second surfaces with an
5 adhesive layer formed on the first surface;
 - (b) forming bump holes extending through said adhesive layer and said base film, and
a window extending therethrough for mounting a chip;
 - (c) forming wiring patterns on said adhesive layer;
 - (e) forming a patterned photoresist layer on said second surface of said base film so
10 that said bump holes are open;
 - (f) forming bumps connected to said wiring patterns by filling said bump holes with a
conductive material using said photoresist layer as a mask; and
 - (g) removing said photoresist layer.
- 15 2. The method of claim 1, further comprising:
 - (d) covering said wiring patterns with a protection layer.
3. The manufacturing method of claim 1, wherein in said step (f), said bumps are
extending above the second surface of said base film.
20
4. The manufacturing method of claim 1, after said step (g), further comprising
polishing said bumps.
5. The manufacturing method of claim 1, after said step (g), further comprising
25 coating a cover film on the second surface of said base film.